

1156918

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SMD pin header, nominal current: 3 A, test voltage: 500 V AC, number of positions: 50, pitch: 2. 54 mm, color: black, contact surface: Au, contact connection type: Pin, mounting: SMD soldering



Your advantages

- · Reliable mechanical and electrical connections thanks to the double-sided contact system
- · Designed for integration into the SMT soldering process
- · Clear and cost-optimized design
- · Suitable for a multitude of applications
- · Stacked, coplanar or orthogonal PCB connections enable maximum flexibility in the device

Commercial data

Item number	1156918
Packing unit	70 pc
Minimum order quantity	70 pc
Sales key	AA24
Product key	AAXGBB
GTIN	4063151159894
Weight per piece (including packing)	5.15 g
Weight per piece (excluding packing)	2.3 g
Customs tariff number	85366930
Country of origin	CN



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Technical data

Notes

Notes on operation	The permissible voltage during operation depends on the application, taking into consideration the air clearances and
	creepage distances within the scope of insulation requirements in accordance with IEC 60664-1.

Product properties

Product type	SMD pin header
Product family	FQ 2,54D/PV
Number of positions	50
Pitch	2.54 mm
Number of rows	2
Pin layout	Linear pad geometry

Electrical properties

Properties

- P			
	Nominal current I _N	3 A (at 20°C 80-pos.)	
	Contact resistance	20 mΩ	
	Test voltage	500 V AC IEC 60512-4-1:2003-05	

Dimensions

Dimensional drawing	h p
Pitch	2.54 mm
Width [w]	63.5 mm
Height [h]	10.2 mm
Length [I]	7.6 mm
Installed height	8.8 mm
Application	
Contact cover	0.4 mm
Stack height	13.6 mm Tolerance: +1.3 mm (in combination with Range of articles:FQ 2,54D/SV)
Wipe length	1.3 mm
PCB design	
Pad geometry	1.02 x 3.4 mm

Material specifications



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Material data - contact

Note	WEEE/RoHS-compliant, free of whiskers according to IEC 60068-2-82/JEDEC JESD 201
Contact material	Cu alloy
Surface characteristics	Selective coating
Metal surface contact area (top layer)	Gold (Au)
Metal surface contact area (middle layer)	Nickel (Ni)
Metal surface soldering area (top layer)	Tin (Sn)

Material data - housing

3	
Color (Housing)	black (9005)
Insulating material	PA
Insulating material group	I
CTI according to IEC 60112	600
Flammability rating according to UL 94	V0

Connector

Connection 1

Insulating material	PA
CTI according to IEC 60112	600

Electrical tests

Thermal test | Test group C

Specification	IEC 60512-5-2:2002-02
Tested number of positions	80
Insulation resistance	
Specification	IEC 60512-3-1:2002-02
Insulation resistance, neighboring positions	> 1 GΩ
Air clearances and creepage distances	

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Insulating material group	I
Minimum value for clearance and creepage distance	0.4 mm

Mechanical tests

Insertion and withdrawal forces

Result	Test passed
No. of cycles	100
Insertion strength per pos. approx.	2.9 N
Withdraw strength per pos. approx.	2.9 N

۰	sual inspection		
	Specification	IEC 60512-1-1:2002-02	
	Result	Test passed	



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Specification	IEC 60512-1-2:2002-02
Result	Test passed

Environmental and real-life conditions

Vibration test

Specification	IEC 60068-2-6:2007-12
Frequency	10 - 55 - 10 Hz
Sweep speed	1 octave/min
Amplitude	1.52 mm
Acceleration	181 m/s²
Test duration per axis	2 h
Test directions	X-, Y- and Z-axis

Durability test

Specification	IEC 60512-9-1:2010-03 (following)
Contact resistance R ₁	20 mΩ
Contact resistance R ₂	30 mΩ
Insertion/withdrawal cycles	100
Insulation resistance, neighboring positions	> 1 GΩ

Ambient conditions

Ambient temperature (operation)	-40 °C 125 °C
Ambient temperature (storage/transport)	-40 °C 70 °C
Relative humidity (storage/transport)	30 % 70 %
Ambient temperature (assembly)	-5 °C 100 °C

Mounting

Mounting type	SMD soldering
Pin layout	Linear pad geometry

Processing notes

Process	Reflow soldering
Moisture Sensitive Level	MSL 1
Classification temperature T _c	260 °C

Packaging specifications

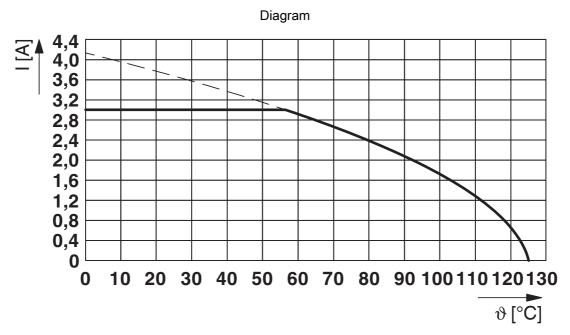
Type of packaging	Tube magazine



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Drawings



Type: FQ 2,54D/...-SV-1020-1-BT with FQ 2,54D/...-PV- 380-1-BT



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Approvals

To download certificates, visit the product detail page: https://www.phoenixcontact.com/us/products/1156918

cULus Recognized Approval ID: E118976					
		Nominal voltage U _N	Nominal current I _N	Cross section AWG	Cross section mm ²
keine					
		30 V	3 A	-	-



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Classifications

ECLASS

	ECLASS-13.0	27460201	
	ECLASS-15.0	27460201	
ETIM			
	ETIM 9.0	EC002637	
UNSPSC			
	UNSPSC 21.0	39121400	



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Environmental product compliance

EU RoHS

Fulfills EU RoHS substance requirements	Yes, No exemptions			
China RoHS				
Environment friendly use period (EFUP)	EFUP-E			
	No hazardous substances above the limits			
EU REACH SVHC				
REACH candidate substance (CAS No.)	No substance above 0.1 wt%			

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